ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSSOP 8-LEAD					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	1,000	500,000	200°C + N2	0	0.00
HAST	4,705	476,000	130°C, 85%RH	0	0.00
Pressure Pot	10,380	1,006,080	121°, 15 PSIG	0	0.00
Solder DUNK	1,665	5,115	260°C, 10SEC	0	0.00
Solderability	1,590	13,200	883 M2003	0	0.00
Temp Cycle	10,586	4,815,415	−65°C−150°C	0	0.00
Thermal Shock	2,400	250,000	−60°C−150°C	0	0.00